UV Cure Adhesives and Encapsulants

- **Transceivers**
- **Camera Modules**
- **Circuit Boards**
- **Disk Drive**
- **Flex Circuits**

PRODUCT	DESCRIPTION	VISCOSITY 19 s^{-1} (cP)	T_g TAN δ (ºC)	CURE SCHEDULE	POT LIFE @ 25ºC (hr)
UV Cure Adhesives and Chip Encapsulants					
535-10M-1	High viscosity elastomeric adhesive for applications requiring extremely low warpage and stress	80,000	5	UV and/or 30 min @ 120ºC	72
DC-4261	Dam material for dam & fill chip encapsulation. Good for smart cards and general circuit assembly applications	10,000	112	UV and/or 30 min @ 150ºC	72
DC-4262	Fill material for dam & fill chip encapsulation. Good for smart cards and general circuit assembly applications	3,500	72	UV and/or 30 min @ 150ºC	73
EC-9519	Clear flexible UV cure encapsulant / adhesive	4,000	NT	UV	0.3
Photonic Active Alignment and Camera Module Assembly Adhesives					
631-188-3	High T_g, low CTE (α_1 ($<T_g$) ≈ 14ppm/ºC), dimensionally stable dual cure for Active alignment, camera module and general electronics assembly applications	50,000	150	UV and/or 60 min @ 120ºC	24
631-184-26 R&D	Low CTE (α_1 ($<T_g$) ≈ 15ppm/ºC), dimensionally stable dual cure for photonic active alignment and camera module. Improved adhesion and depth of cure	50,000	136	UV and/or 60 min @ 120ºC	24
631-184-32 R&D	High T_g, low CTE (α_1 ($<T_g$) ≈ 15ppm/ºC), dimensionally stable dual cure for photonic active alignment and camera module	35,000	185	UV and/or 60 min @ 120ºC	24